

PATENT

Docket No.:JCLA8534-D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Applicant : JIN-YUAN LEE et al.
Filed : Herewith
For : INTEGRATED CHIP PACKAGE STRUCTURE USING
ORGANIC SUBSTRATE AND METHOD OF
MANUFACTURING THE SAME

PRELIMINARY AMENDMENT

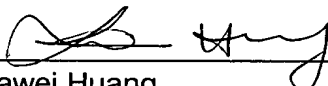
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Prior to the examination on merits, please amend the above-identified application as shown in the attached sheets. No new matter has added through the amendment. Entry of the amendment is requested.

Respectfully submitted,

Dated: 12/3/2003

By: 
Jiawei Huang
Registration No. 43,330

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